

C0603C330K3RACTU

Specifications

Insulation Resistance

Aliases (C0603C330K3RAC7867) SMD Comm X7R, Ceramic, 33 pF, 10%, 25 VDC, X7R, SMD, MLCC, Temperature Stable, Class II, 0603, 0.5 mm



General Information	
Series	SMD Comm X7R
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Class II
Features	Temperature Stable, Class II
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	4.8 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0603
L	1.6mm +/-0.15mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.07mm
S	0.5mm MIN
В	0.35mm +/-0.15mm

33 pF
33 pi
1 kHz 1.0Vrms
10%
25 VDC
62.5 VDC
-55/+125°C
X7R
15%, 1kHz 1.0Vrms
3.5% 1 kHz 1.0Vrms
3% Loss/Decade Hour: Referee Time is 48 Hours

100 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Generated 05/29/2025 © 2006 - 2025 YAGEO